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(54) **MULTILAYER RESIN SUBSTRATE AND
ELECTRONIC COMPONENT**

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(57) **ABSTRACT**

A multilayer resin substrate includes first and second substrates joined to overlap each other, a first signal electrode on a joint surface between the first and second substrates, a first via-conductor in the first substrate and joined to the first signal electrode, a first ground electrode in or on the second substrate and overlapping the first signal electrode, a first floating electrode in the second substrate and between the first signal electrode and the first ground electrode. The first signal electrode includes a first joint joined to the first via-conductor and a wiring portion extending in a signal transmission direction. In a line-width direction transverse to the signal transmission direction, the first joint has a line width greater than that of the wiring portion. When viewed in the thickness direction, the first floating electrode overlaps the first joint of the first signal electrode.

